



Power MOSFETS

DATASHEET

LM1A090NAQ8A

N-Channel
Enhancement Mode MOSFET

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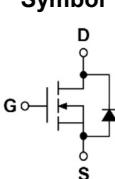


Quality Management Systems
ISO 9001:2015 Certificate

LM1A090NAQ8A

N-Channel Enhancement Mode MOSFET

Pin Description

SOP-8L (TOP view)	Symbol	Symbol	N-Channel	Unit
			V_{DSS}	100
			$R_{DS(ON)}\text{-Max}$	8.4
			I_D	10.7

Feature

- Optimized high performance of $R_{DS(on)}$ and Q_g
- Reliable and Rugged
- ROHS Compliant & Halogen-Free
- 100% UIS Tested

Applications

- Motor drivers
- DC DC converter

Ordering Information

Orderable Part Number	Package Type	Form	Shipping	Marking
LM1A090NAQ8A	SOP-8L	Tape & Reel	3000 / Tape & Reel	1A090 <input type="checkbox"/> <input type="checkbox"/> <input type="checkbox"/> <input type="checkbox"/> <input type="checkbox"/>

Note : = Lot Code

Absolute Maximum Ratings ($T_J=25^\circ\text{C}$ Unless Otherwise Noted)

Symbol	Parameter	N-Channel	Unit
V_{DSS}	Drain-Source Voltage	100	V
V_{GSS}	Gate-Source Voltage	± 20	
T_J	Maximum Junction Temperature	150	$^\circ\text{C}$
T_{STG}	Storage Temperature Range	-55 to 150	$^\circ\text{C}$
I_S	Diode Pulse Forward Current	$T_A=25^\circ\text{C}$	A
I_{DM}^{\circledR}	Pulse Drain Current Tested	$T_A=25^\circ\text{C}$	A
I_D	Continuous Drain Current	$T_A=25^\circ\text{C}$	1.5
		$T_A=70^\circ\text{C}$	27
I_D		$T_A=70^\circ\text{C}$	10.7
		$T_A=25^\circ\text{C}$	6.8
P_D	Maximum Power Dissipation	$T_A=25^\circ\text{C}$	W
		$T_A=70^\circ\text{C}$	1.7
I_{AS}^{\circledR}	Avalanche Current, Single pulse	$L=0.1\text{mH}$	0.7
		$L=0.5\text{mH}$	19
E_{AS}^{\circledR}	Avalanche Energy, Single pulse	$L=0.1\text{mH}$	10
		$L=0.5\text{mH}$	18
		$L=0.1\text{mH}$	25
		$L=0.5\text{mH}$	mJ

Thermal Characteristics

Symbol	Parameter	Rating	Unit
$R_{\theta JA}^{\circledR}$	Thermal Resistance-Junction to Ambient	$t \leq 10\text{s}$	$^\circ\text{C/W}$
	Thermal Resistance-Junction to Ambient	Steady State	

Note ① : Max. current is limited by junction temperature

Note ② : UIS tested and pulse width are limited by maximum junction temperature 150°C

Note ③ : Surface Mounted on 1in² FR-4 board with 1oz.

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N-Channel Electrical Characteristics ($T_J=25^\circ\text{C}$ Unless Otherwise Noted)

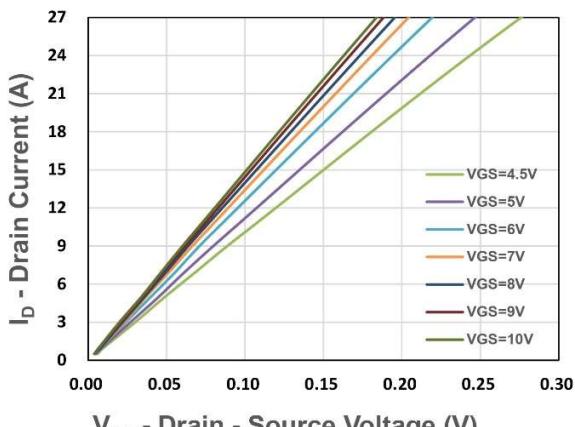
Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
Static Electrical Characteristics						
BV_{DSS}	Drain-Source Breakdown Voltage	$V_{\text{GS}}=0\text{V}$, $I_{\text{DS}}=250\mu\text{A}$	100	-	-	V
I_{DSS}	Zero Gate Voltage Drain Current	$V_{\text{DS}}=80\text{V}$, $V_{\text{GS}}=0\text{V}$	-	-	1	μA
$V_{\text{GS(th)}}$	Gate Threshold Voltage	$V_{\text{DS}}=V_{\text{GS}}$, $I_{\text{DS}}=250\mu\text{A}$	1	2	3	V
I_{GSS}	Gate Leakage Current	$V_{\text{GS}}=\pm 20\text{V}$, $V_{\text{DS}}=0\text{V}$	-	-	± 100	nA
$R_{\text{DS(ON)}}^{\circledast}$	Drain-Source On-state Resistance	$V_{\text{GS}}=10\text{V}$, $I_{\text{DS}}=12\text{A}$	-	7	8.4	$\text{m}\Omega$
		$V_{\text{GS}}=4.5\text{V}$, $I_{\text{DS}}=8\text{A}$	-	10	13	
g_{fs}	Forward Transconductance	$V_{\text{DS}}=5\text{V}$, $I_{\text{DS}}=12\text{A}$	-	34	-	S
Dynamic Characteristics [®]						
R_{G}	Gate Resistance	$V_{\text{GS}}=0\text{V}$, $V_{\text{DS}}=0\text{V}$, Freq.=1MHz	-	2	-	Ω
C_{iss}	Input Capacitance	$V_{\text{GS}}=0\text{V}$, $V_{\text{DS}}=50\text{V}$, Freq.=1MHz	-	1932	-	pF
C_{oss}	Output Capacitance		-	387	-	
C_{rss}	Reverse Transfer Capacitance		-	30	-	
$t_{\text{d(ON)}}$	Turn-on Delay Time	$V_{\text{GS}}=10\text{V}$, $V_{\text{DS}}=50\text{V}$, $I_{\text{D}}=1\text{A}$, $R_{\text{GEN}}=3\Omega$	-	10.2	-	nS
t_{r}	Turn-on Rise Time		-	20	-	
$t_{\text{d(OFF)}}$	Turn-off Delay Time		-	31	-	
t_{f}	Turn-off Fall Time		-	14	-	
Q_{g}	Total Gate Charge	$V_{\text{GS}}=4.5\text{V}$, $V_{\text{DS}}=50\text{V}$ $I_{\text{D}}=20\text{A}$	-	22.8	-	nC
Q_{g}	Total Gate Charge	$V_{\text{GS}}=10\text{V}$, $V_{\text{DS}}=50\text{V}$, $I_{\text{D}}=20\text{A}$	-	41.8	-	
Q_{gs}	Gate-Source Charge		-	5.6	-	
Q_{gd}	Gate-Drain Charge		-	12.3	-	
Source-Drain Characteristics						
$V_{\text{SD}}^{\circledast}$	Diode Forward Voltage	$I_{\text{SD}}=12\text{A}$, $V_{\text{GS}}=0\text{V}$	-	0.8	1.1	V
t_{rr}	Reverse Recovery Time	$I_{\text{F}}=20\text{A}$, $V_{\text{R}}=50\text{V}$	-	49	-	nS
Q_{rr}	Reverse Recovery Charge	$dI_{\text{F}}/dt=100\text{A}/\mu\text{s}$	-	58.7	-	nC

Note ④ : Pulse test (pulse width $\leq 300\mu\text{s}$, duty cycle $\leq 2\%$).

Note ⑤ : Guaranteed by design, not subject to production testing.

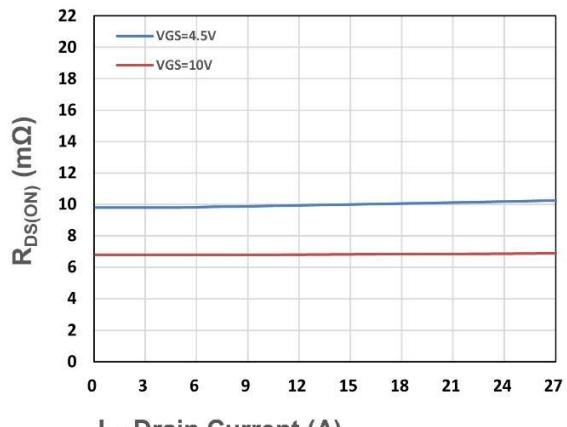
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N-Channel Typical Characteristics



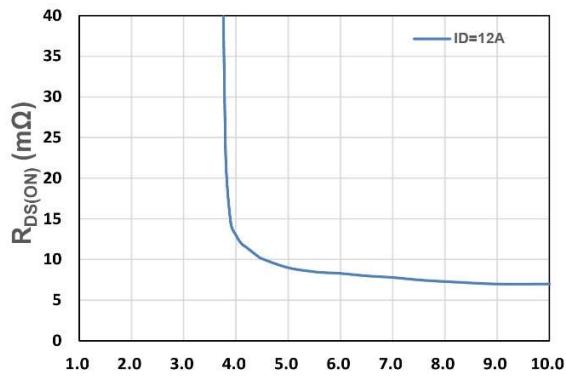
V_{DS} - Drain - Source Voltage (V)

Figure 1. Output Characteristics



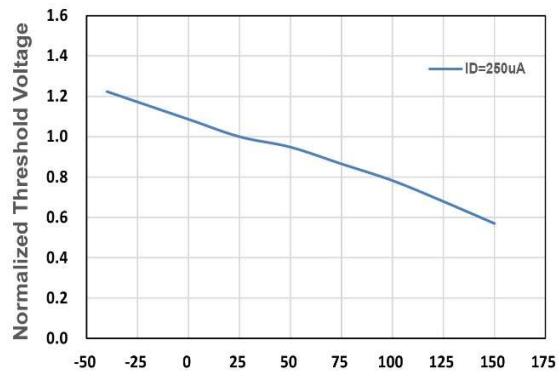
I_D - Drain Current (A)

Figure 2. On-Resistance vs. ID



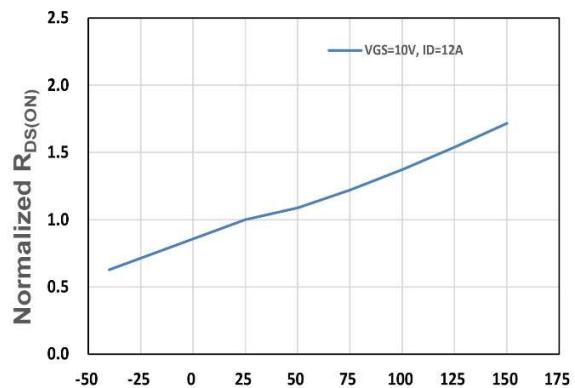
V_{GS} - Gate - Source Voltage (V)

Figure 3. On-Resistance vs. VGS



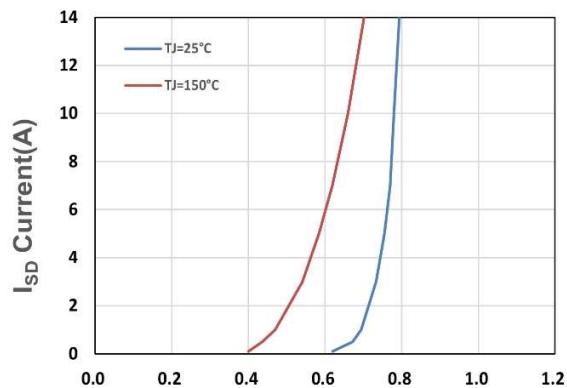
T_j , Junction Temperature(°C)

Figure 4. Gate Threshold Voltage



T_j , Junction Temperature(°C)

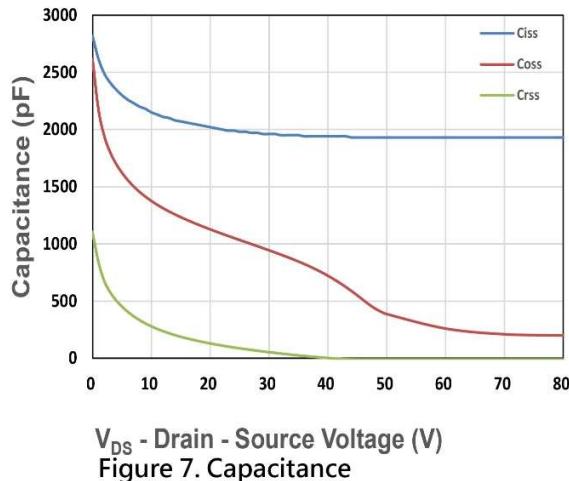
Figure 5. Drain-Source On Resistance



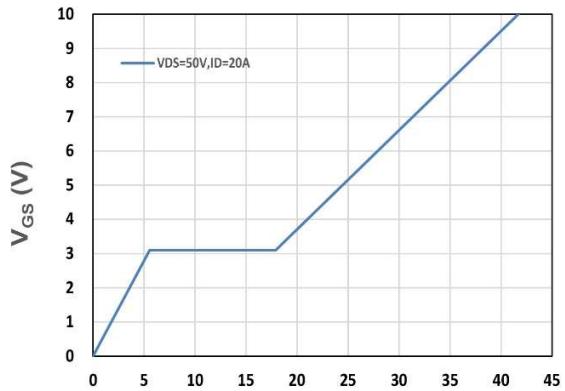
V_{SD} , Source-Drain Voltage(V)

Figure 6. Source-Drain Diode Forward

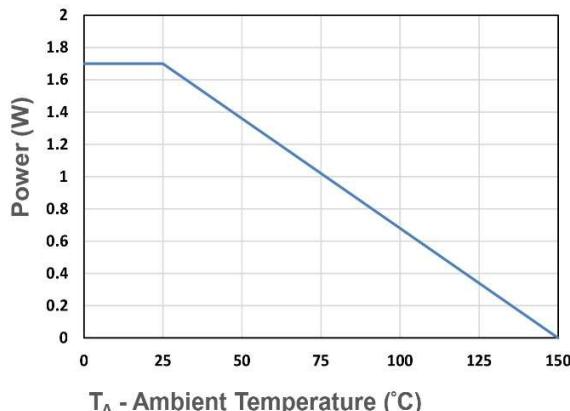
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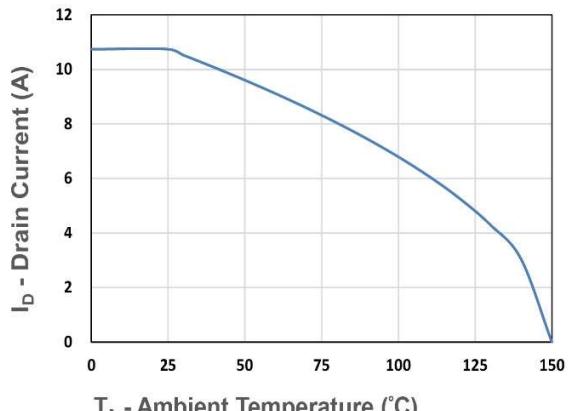
V_{DS} - Drain - Source Voltage (V)
Figure 7. Capacitance



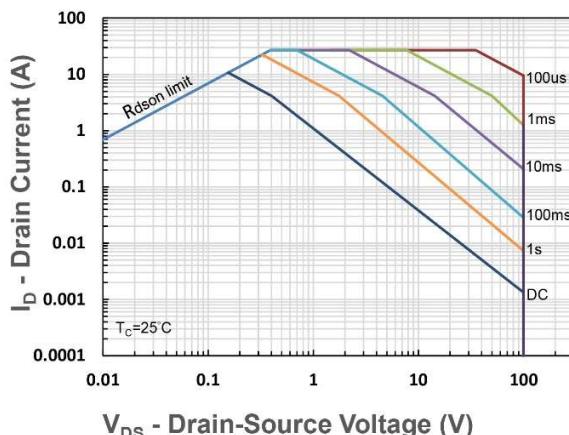
Q_g , Total Gate Charge (nC)
Figure 8. Gate Charge Characteristics



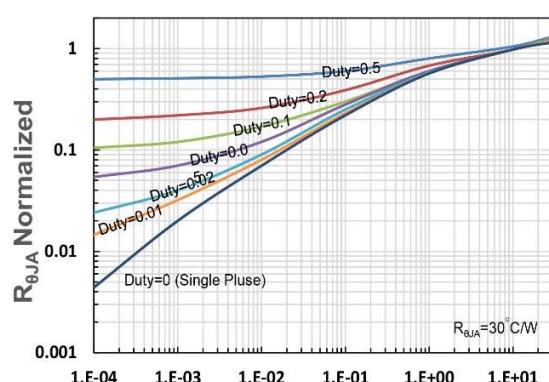
T_A - Ambient Temperature (°C)
Figure 9. Power Dissipation



T_A - Ambient Temperature (°C)
Figure 10. Drain Current



I_D - Drain Current (A)
 V_{DS} - Drain-Source Voltage (V)
Figure 11. Safe Operating Area



t_1 , Square Wave Pulse Duration(s)
Figure 12. R_{eJA} Transient Thermal Impedance